

Product Change Notification / LIAL-24FVEV066

Date:

06-Dec-2022

Product Category:

8-bit Microcontrollers, Capacitive Touch Sensors

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5064.001 Final Notice: Qualification of G700LA as a new mold compound material for selected ATMEGA1xx, ATMEGA3xx, ATMEGA6xx, ATMEGA8xx, AT42QTxx, and AT89LPxx device families available in 44L VQFN (7x7x1mm) package at ASCL assembly site.

Affected CPNs:

LIAL-24FVEV066_Affected_CPN_12062022.pdf LIAL-24FVEV066_Affected_CPN_12062022.csv

Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of G700LA as a new mold compound material for selected ATMEGA1xx, ATMEGA3xx, ATMEGA6xx, ATMEGA8xx, AT42QTxx, and AT89LPxx device families available in 44L VQFN (7x7x1mm) package at ASCL assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change			
Assembly Site	ASE Group Chung-Li (ASCL)	ASE Group Chung-Li (ASCL)			
Wire Material	Au/Cu/PdCu	Au/Cu/PdCu			
Die Attach Material	EN-4900GC	EN-4900GC			
Molding Compound Material	CEL-9240	G700LA			
Lead-Frame Material	C194	C194			

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve manufacturability by qualifying G700LA as new mold compound material.

Change Implementation Status: In Progress

Estimated First Ship Date: December 29, 2022 (date code: 2253)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	April 2022					>	December 2022				
Workweek	14	15	16	17	18		49	50	51	52	53
Initial PCN Issue Date					Х						
Qual Report Availability								Х			
Final PCN Issue Date								Х			
Estimated											v
Implementation Date											Х

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: April 27, 2022: Issued initial notification.

December 6, 2022: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on December 29, 2022.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_LIAL-24FVEV066_Qualification Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. LIAL-24FVEV066 - CCB 5064.001 Final Notice: Qualification of G700LA as a new mold compound material for selected ATMEGA1xx, ATMEGA3xx, ATMEGA6xx, ATMEGA8xx, AT42QTxx, and AT89LPxx device families available in 44L VQFN (7x7x1mm) package at ASCL assembly site.

Affected Catalog Part Numbers (CPN)

ATMEGA324PA-MN ATMEGA324PA-MNR AT42QT5480-MUR AT42QT18C15-MUR ATMEGA16-16MQ ATMEGA8535L-8MU ATMEGA8535-16MU ATMEGA8535L-8MUR ATMEGA8535-16MUR ATMEGA162-16MU ATMEGA162V-8MU ATMEGA162-16MUR ATMEGA162V-8MUR ATMEGA324PV-10MUA1 ATMEGA324P-20MU ATMEGA324PV-10MU ATMEGA324P-20MQ ATMEGA324P-20MQR ATMEGA324PV-10MUR ATMEGA324P-20MUR ATMEGA644PV-10MQ ATMEGA644P-20MQ ATMEGA644P-20MQR ATMEGA644PV-10MQR ATMEGA164PV-10MUA0 AT89LP52-20MU AT89LP51-20MU AT89LP51ED2-20MU AT89LP51ID2-20MU AT89LP51RD2-20MU AT89LP51RB2-20MU AT89LP51RC2-20MU AT89LP51IC2-20MU AT89LP6440-20MU AT89LP3240-20MU